

Three-Dimensional Fully-Coupled Electrical and Thermal Transport Model of Dynamic Switching in Oxide Memristors

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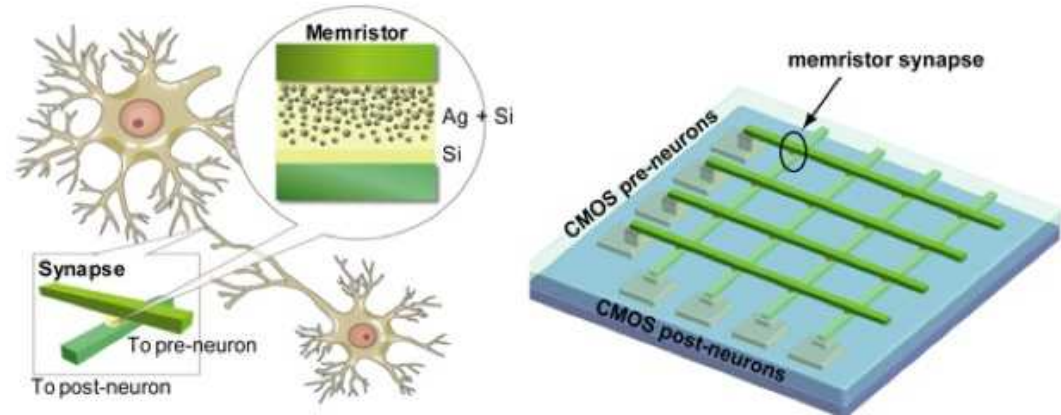
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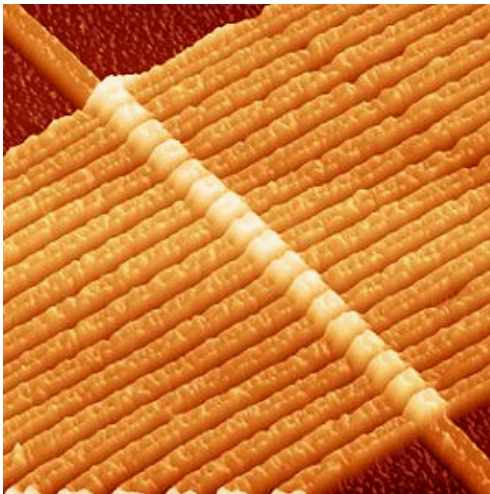
Memristor – New Research Frontier

Brain-Inspired Computing

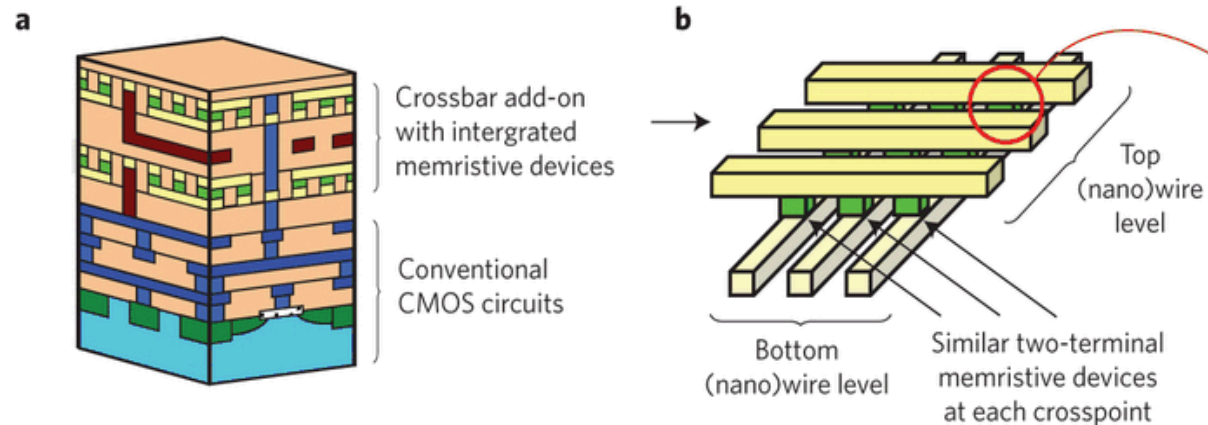
Using memristors as synapse to build computers like nature builds brains



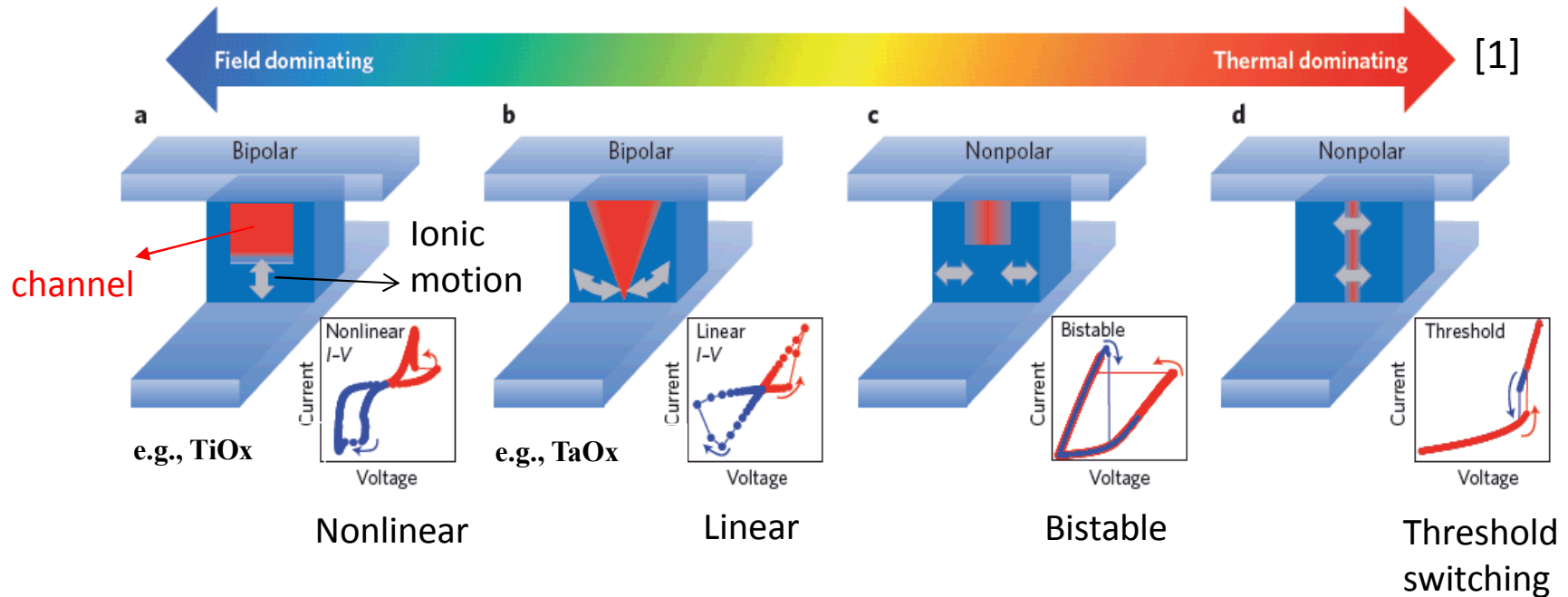
Non-volatile Memory



Hybrid CMOS/Memristor 3D Circuits



Memristor – Complex Switching Process



Complex switching behavior - governed by temporally and spatially intertwined electrical and thermal processes of **electrons, holes, and mobile vacancies**:

- Field drift
- Fick diffusion
- Soret effect
- Joule heating
- High-order effects

NO existing models have captured all these processes and their couplings for **electrons, holes, and mobile vacancies simultaneously** in 3D device structures !

Fully-Coupled Transport Model

We solve, **simultaneously**, the five coupled differential equations:

Poisson (P): $\nabla \cdot \epsilon \nabla (\phi) = -q(p - n + C + z_V N_V)$ \longrightarrow include all charge species

Electron (E): $q \frac{\partial n}{\partial t} = \nabla \cdot \vec{J}_n - qR_{net}$

Hole (H): $q \frac{\partial p}{\partial t} = -\nabla \cdot \vec{J}_p - qR_{net}$

Vacancy (V): $q \frac{\partial N_V}{\partial t} = -\nabla \cdot \vec{J}_V$

time-dependent continuity equations for all carriers

Temperature (T): $\frac{\partial}{\partial t}(c_L T) - \nabla \cdot (\kappa_L \nabla T) = H$

Auxiliary relations:

Field drift

Fick diffusion

Soret effect

$$\begin{aligned}\vec{J}_n &= qn\mu_n \vec{E} + qD_n \nabla n + k_B n \mu_n \nabla T \\ \vec{J}_p &= qp\mu_p \vec{E} - qD_p \nabla p - k_B p \mu_p \nabla T \\ \vec{J}_V &= qN_V \mu_V \vec{E} - qD_V \nabla N_V - qD_V S_V N_V \nabla T\end{aligned}$$

Joule heating due to all carriers

$$H = (\vec{J}_n + \vec{J}_p + \vec{J}_V) \cdot \vec{E} + R_{net}(E_g + 3k_B T)$$

Vacancy Mobility Model

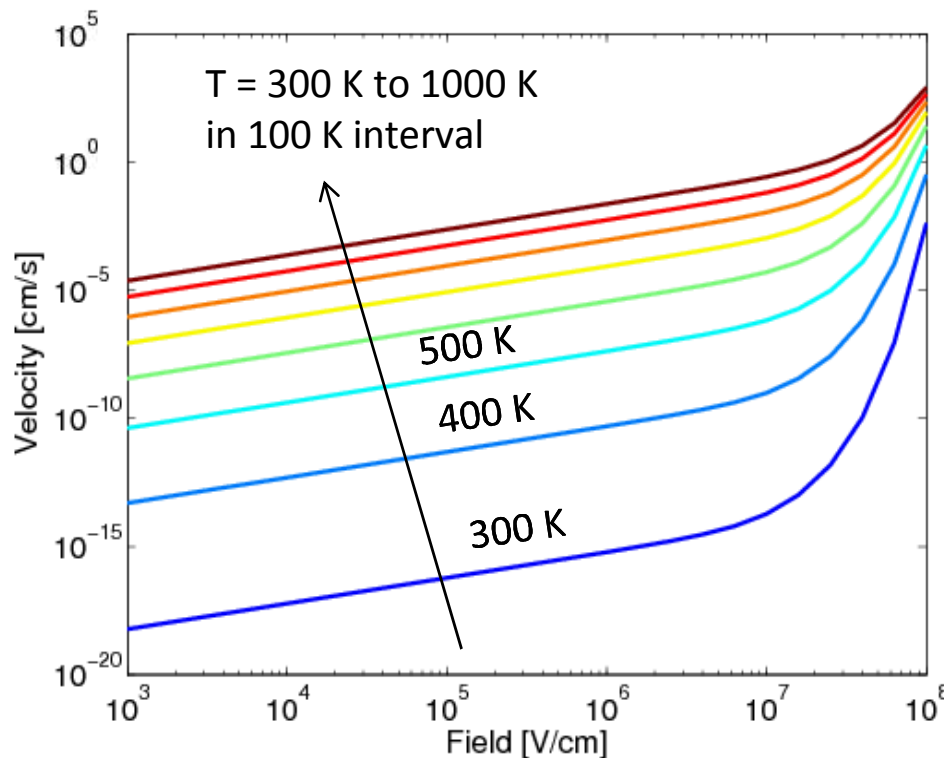
Rigid Point Ion Model (RPI)

Vacancy velocity $v_V = 2 \cdot f \cdot a \cdot \exp\left(\frac{-E_a}{kT}\right) \cdot \sinh\left(\frac{qaE}{kT}\right)$

Vacancy diffusion $D_V = f \cdot a^2 \cdot \exp\left(\frac{-E_a}{kT}\right)$

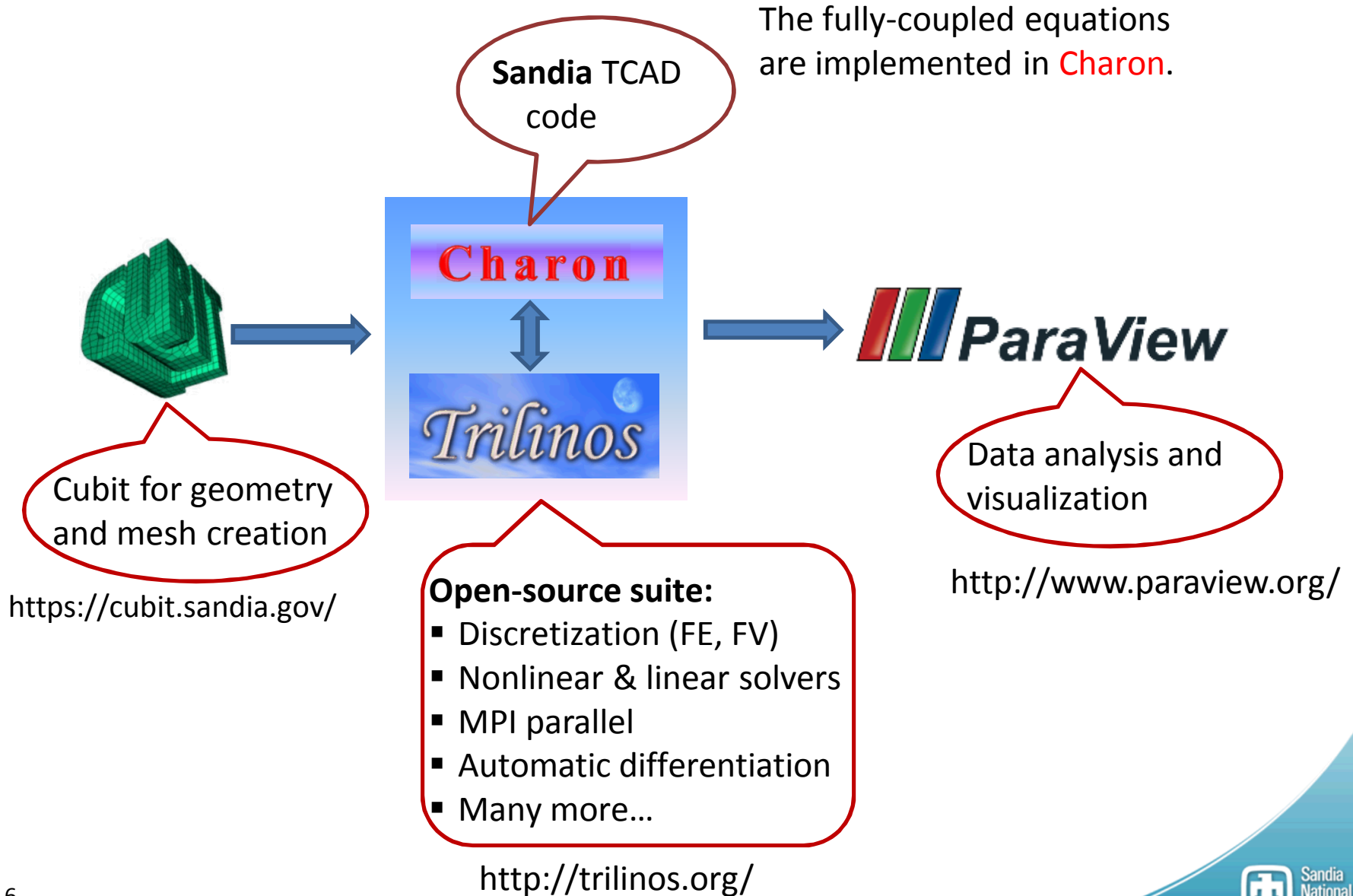
Vacancy activation energy E_a

Electric field E

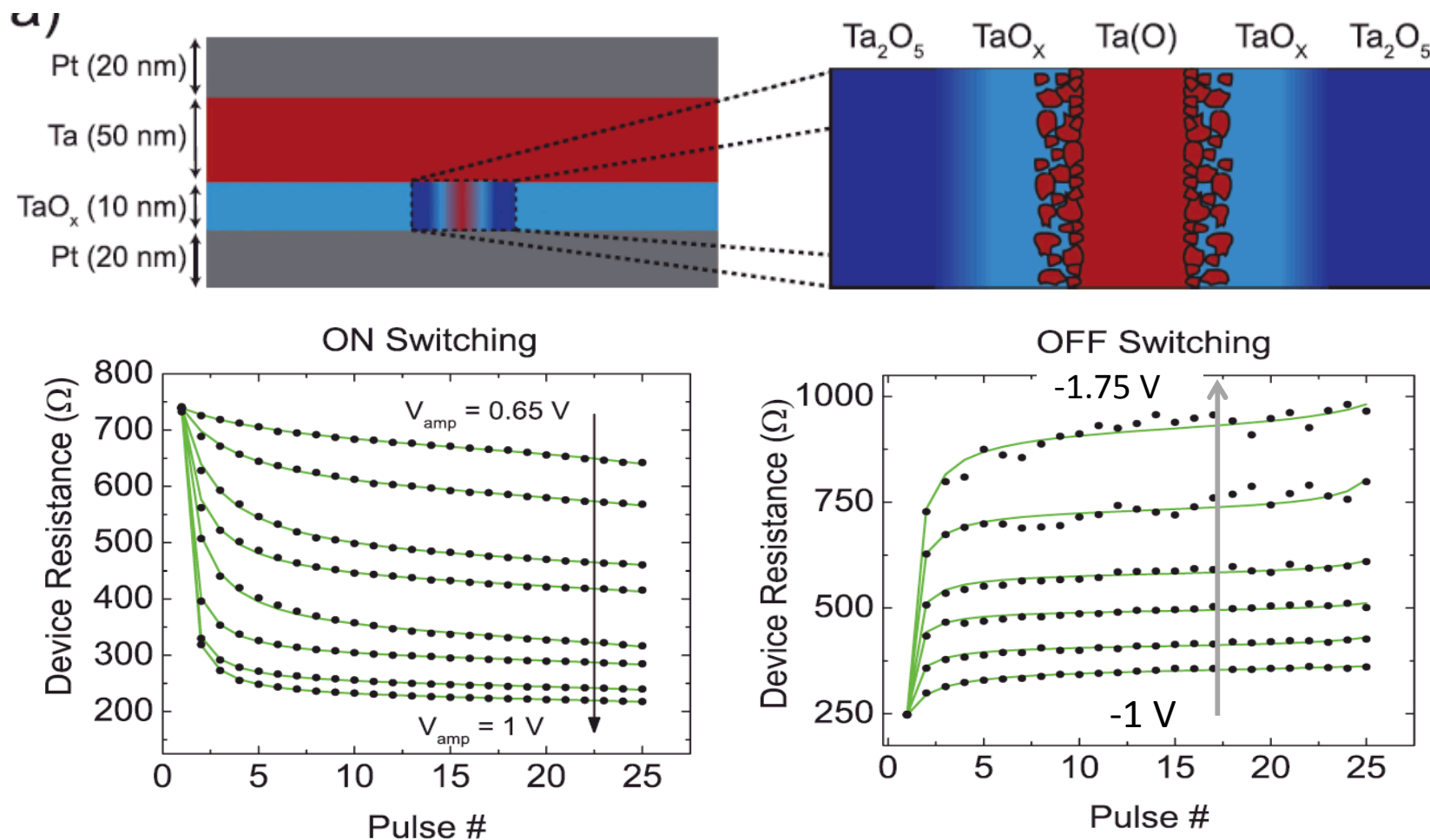


- Vacancy motion exponentially depends on temperature, and field when the field exceeds a critical value

Charon Device Simulator



Experimental Resistance



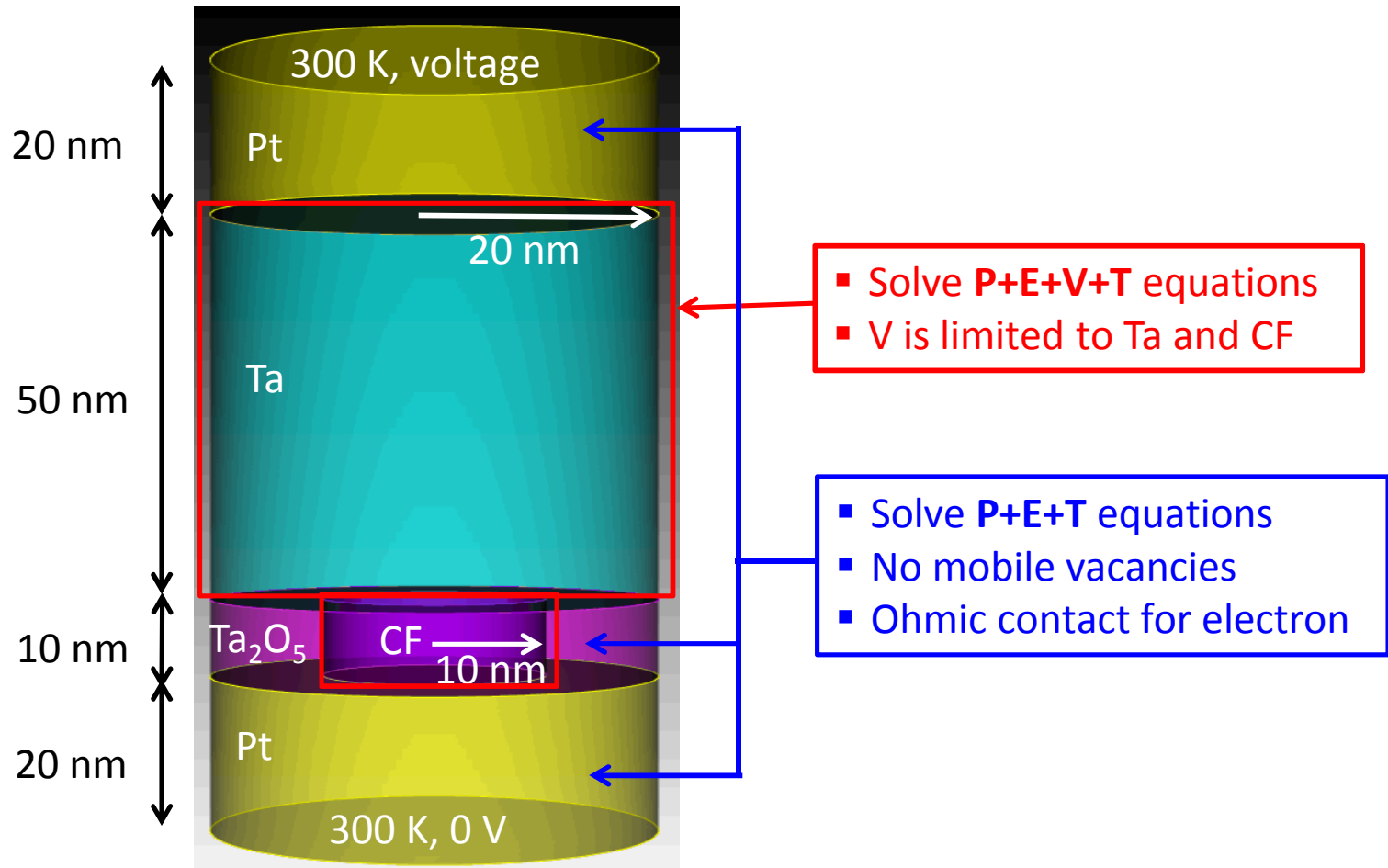
- Experimental ON-resistance **decreases** with time and increasing voltage
- Experimental OFF-resistance **increases** with time and increasing voltage

[2] Patrick R. Mickel et al., A physical model of switching dynamics in tantalum oxide memristive devices, APL **102**, 223502 (2013).

Modeling Goal

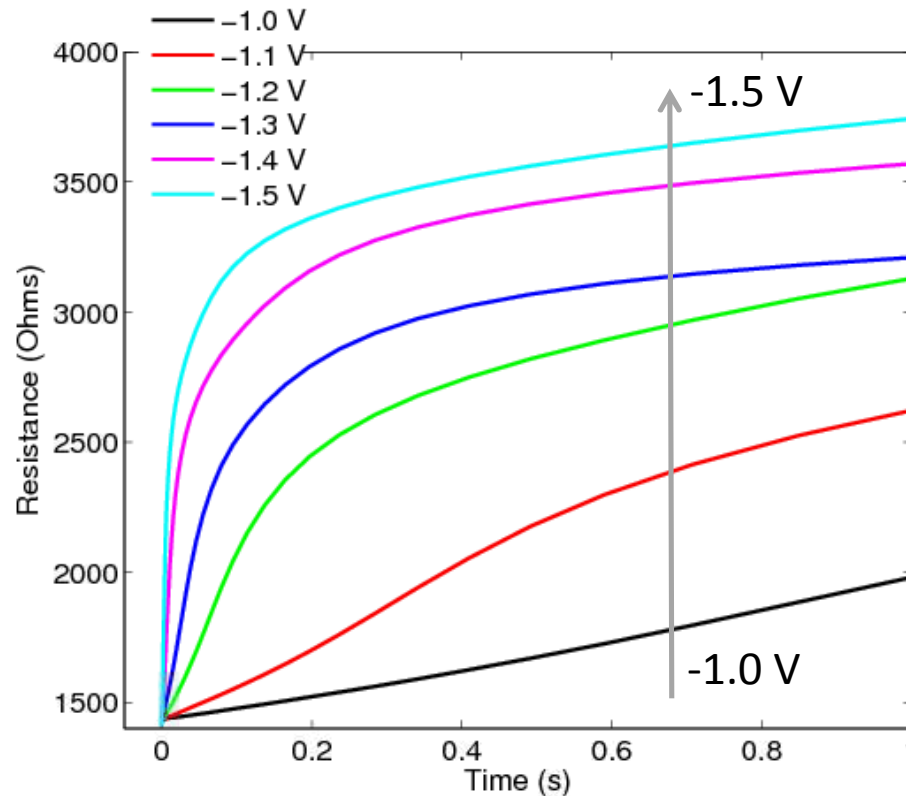
- ❑ Demonstrate qualitatively the **resistance increases with time and increasing voltage** during OFF switching in a TaOx memristor
- ❑ Demonstrate qualitatively the **resistance decreases with time and increasing voltage** during ON switching in a TaOx memristor
- ❑ Demonstrate qualitatively the **current-voltage hysteresis** under triangular voltage sweep in a TaOx memristor

TaOx Device Structure



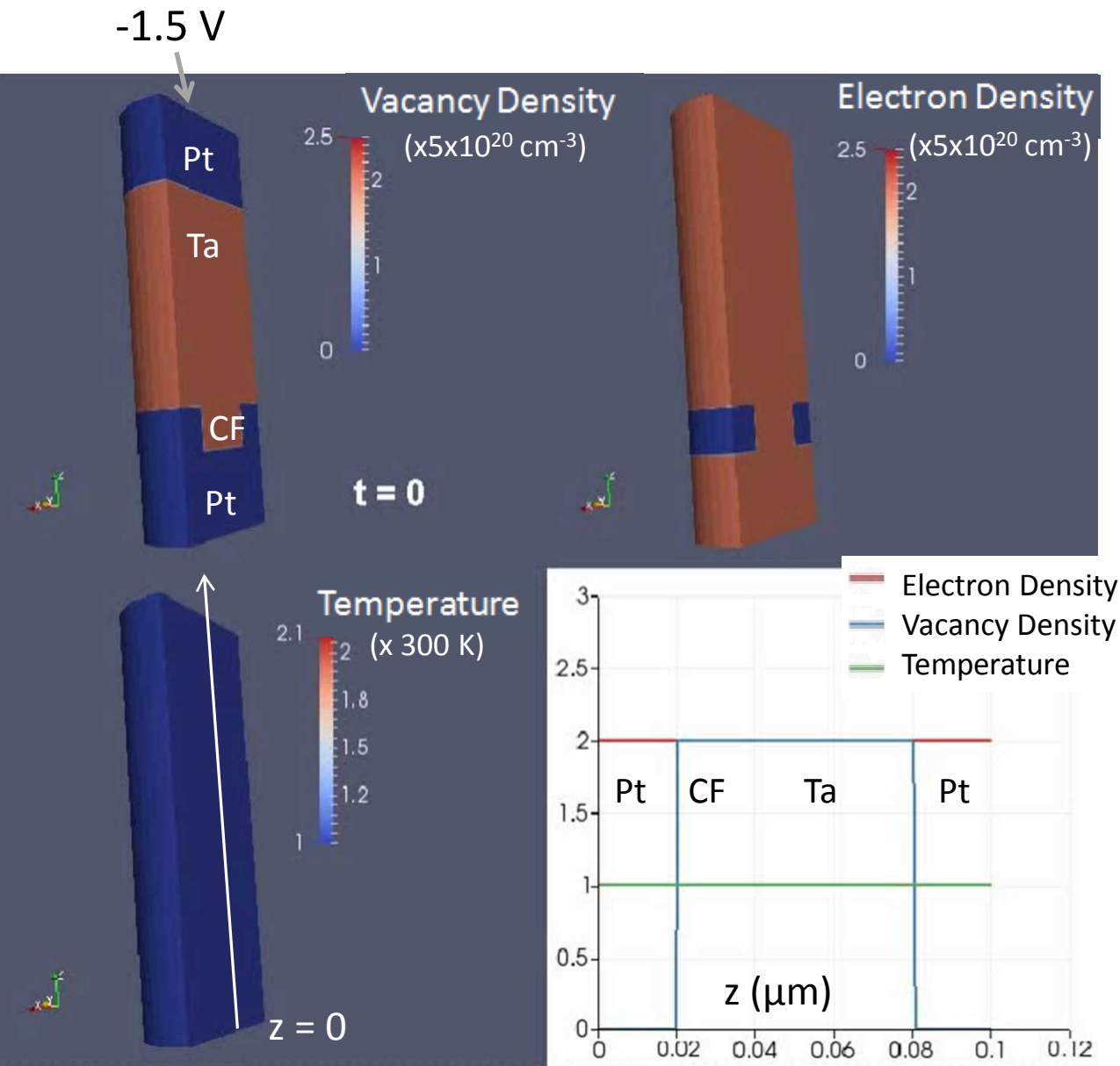
[2] Patrick R. Mickel et al., A physical model of switching dynamics in tantalum oxide memristive devices, APL **102**, 223502 (2013).

OFF-Switching Resistance Evolution



- Resistance increases with time and increasing voltage during OFF-switching, consistent with experimental observation

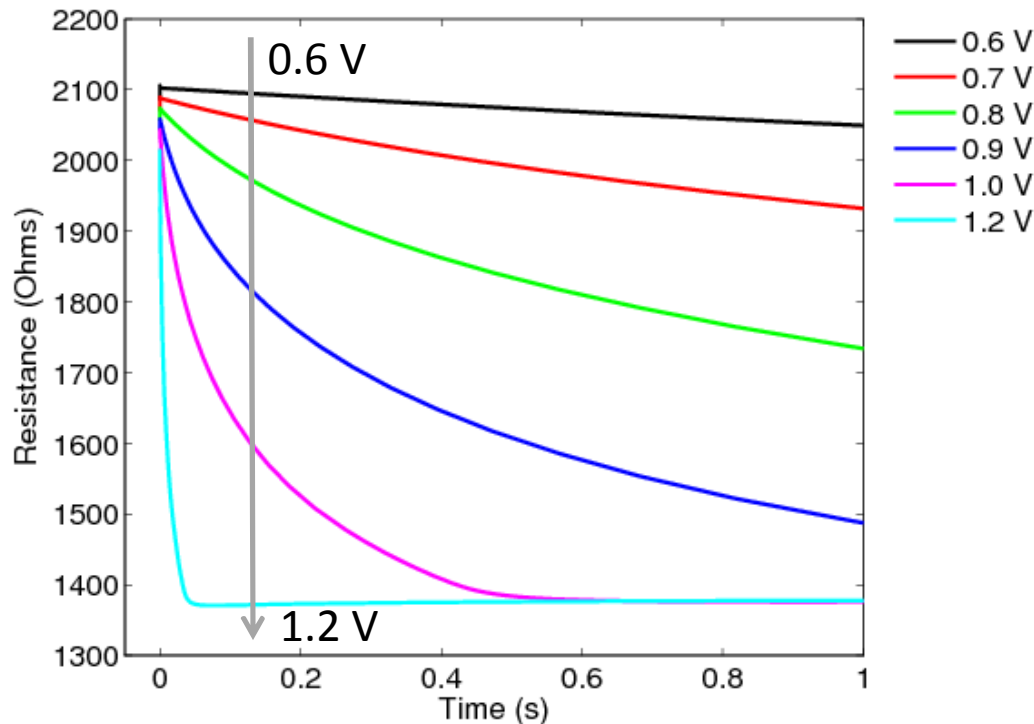
What Happens During OFF-Switching



OFF-Switching:

- Initial temperature increase occurs on the order of 100 ps, and initial heating is broad in space
- Vacancies near the peak temp. start to move around μs , and move away from CF into Ta
- CF first has a density gap formed, and eventually is depleted of vacancies, resulting in OFF state
- As CF becomes more resistive, heating is more localized in CF

ON-Switching Resistance Evolution

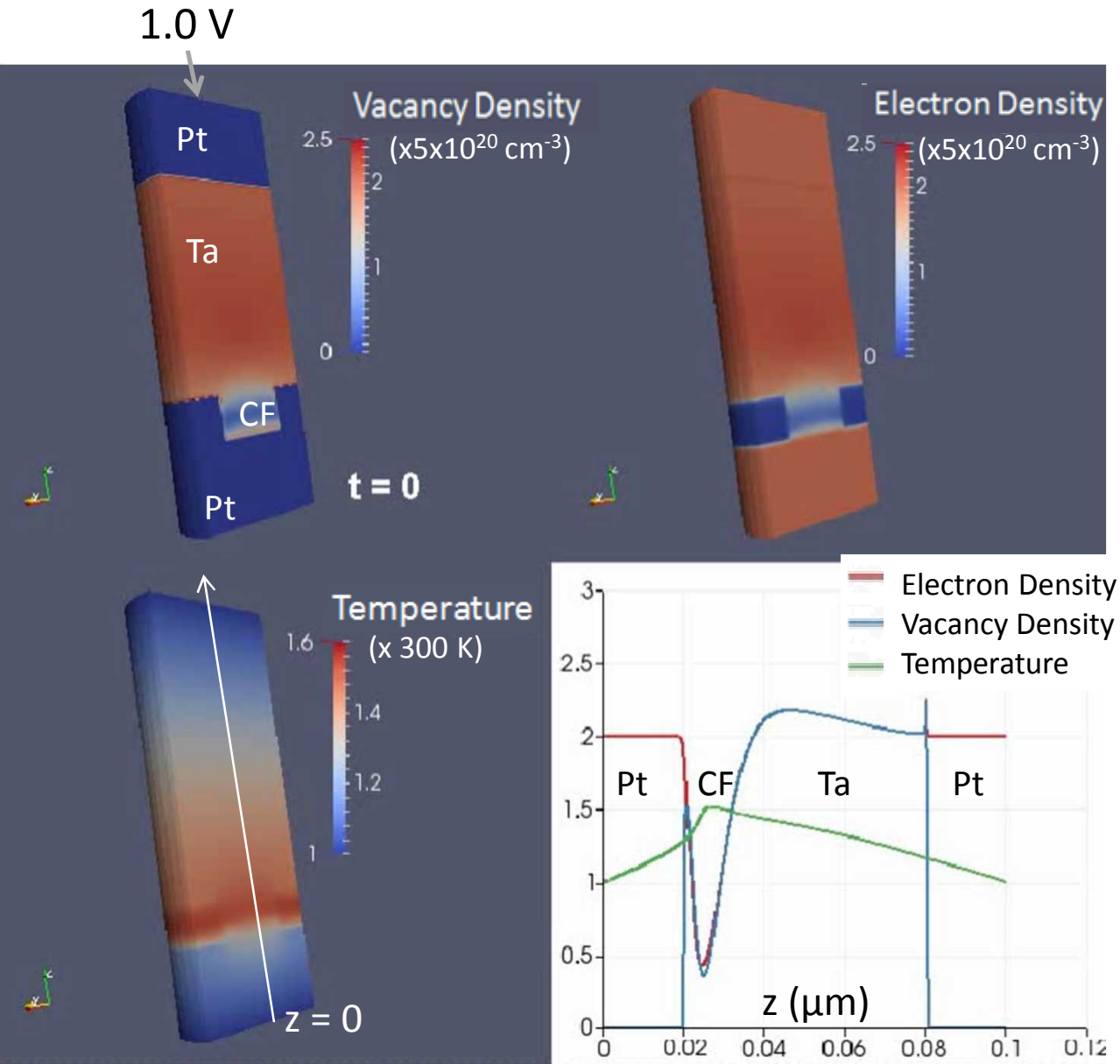


During ON-switching, vacancy diffusion is increased with vacancy density to avoid unphysical piling-up:

$$D_V = \frac{D_{rpi}}{1 - \frac{N_V}{N_{max}}}$$

- ON-resistance decreases with time for a given voltage, and decreases faster with time for higher voltage, consistent with experimental observation

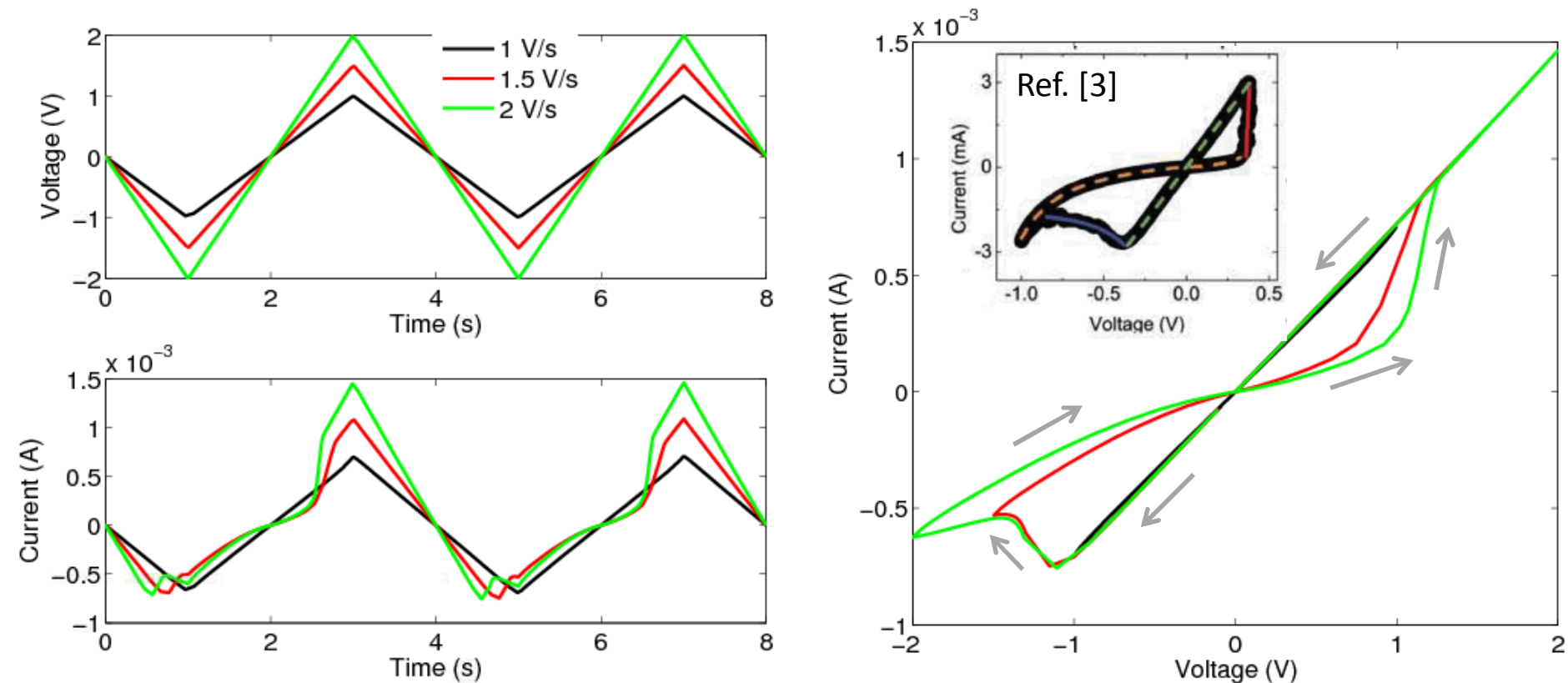
What Happens During ON-Switching



ON-Switching:

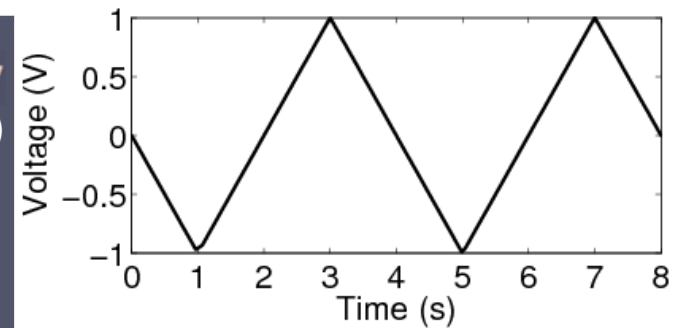
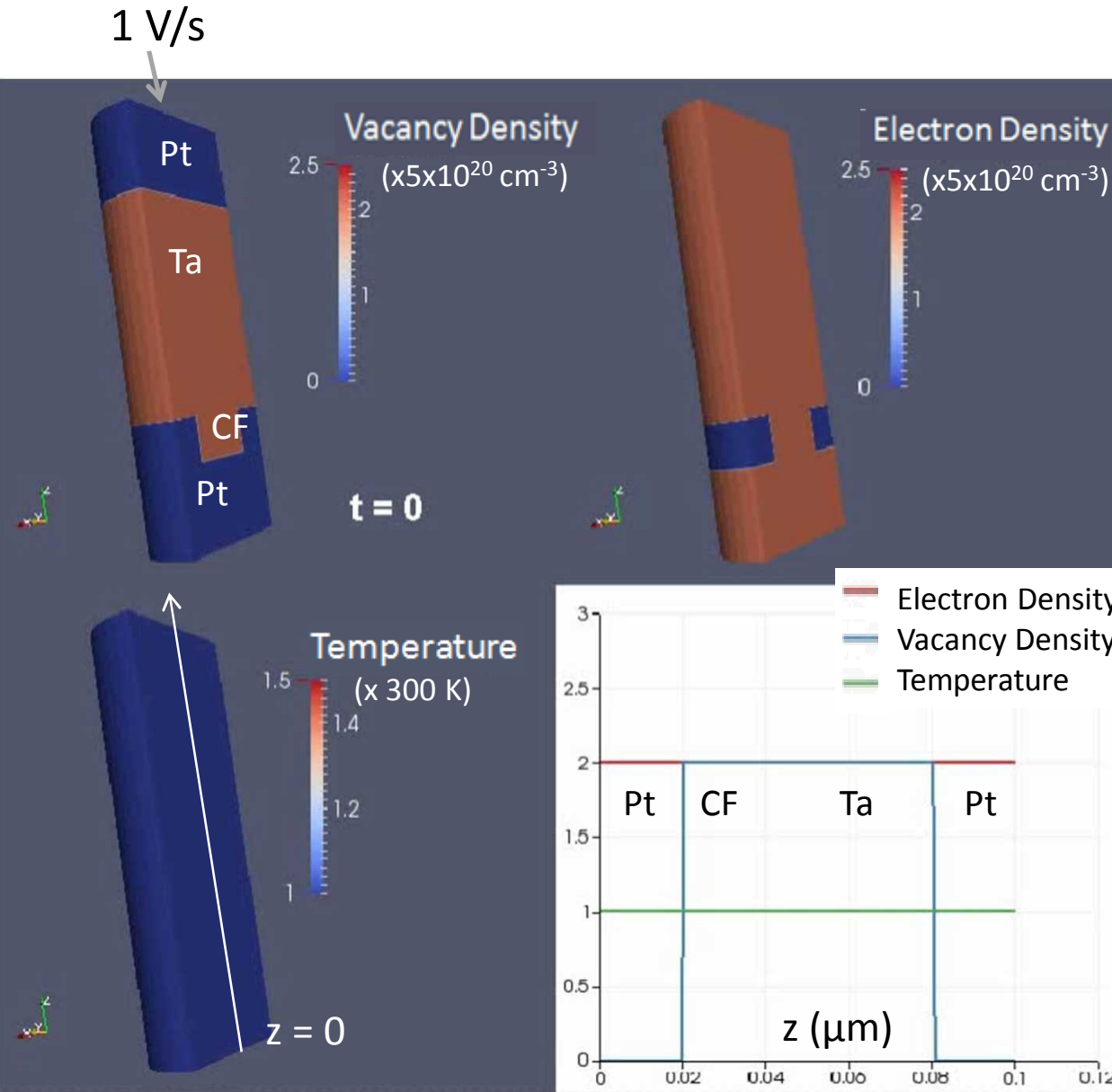
- Starting with an OFF-state, temp. increases on the order of 100 ps
- Vacancies move from Ta into CF to fill in the gap according to RPI model
- As CF becomes more conductive, heating is more spread in space

Current-Voltage Hysteresis



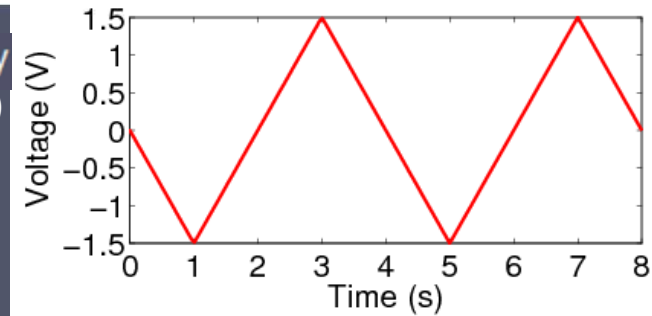
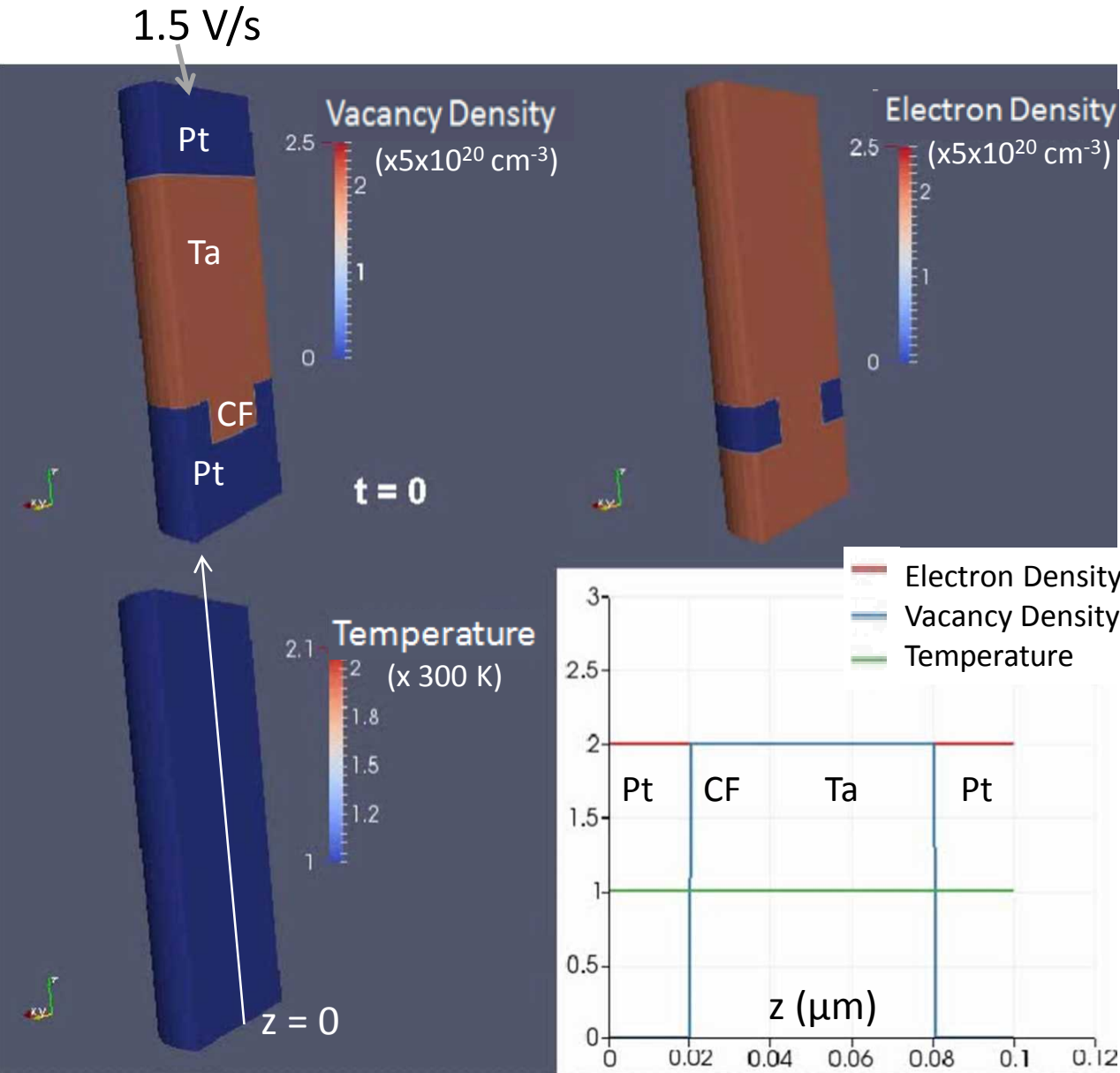
- Current-voltage hysteresis is NOT observed for the 1 V/s voltage ramping
- Current-voltage hysteresis is clearly observed for the 1.5 V/s and 2 V/s cases, and shows qualitative agreement with experimental result

What Happens During Voltage Sweep



- Given the 1 V/s triangular voltage, device never turned off during negative voltage, due to insufficient heating

What Happens During Voltage Sweep



- Given the 1.5 V/s triangular voltage, device fully turned off during negative voltage, and was able to turn on during positive voltage

Conclusion

